



**Description**

The HSBA0139 uses advanced trench MOSFET technology to provide excellent  $R_{DS(ON)}$  and gate charge for use in a wide variety of other applications.

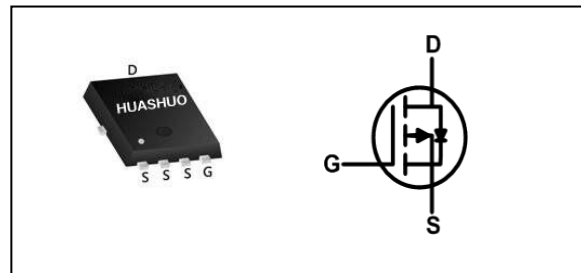
The HSBA0139 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

**Product Summary**

$V_{DS}$	-100	V
$R_{DS(ON),typ}$	42	mΩ
$I_D$	-30	A

**PRPAK5\*6 Pin Configuration**



**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-100	V
$V_{GS}$	Gate-Source Voltage	±20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ -10V_1$	-30	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ -10V_1$	-19	A
$I_D@T_A=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ -10V_1$	-8	A
$I_D@T_A=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ -10V_1$	-6.5	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-45	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	345	mJ
$I_{AS}$	Avalanche Current	-28	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation <sup>4</sup>	83	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	1.22	°C/W



**P-Ch 100V Fast Switching MOSFETs**

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
B <sub>VDS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-100	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	---	42	50	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A	---	46	55	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.2	-1.8	-2.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-50	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-10V, I <sub>D</sub> =-10A	---	32	---	S
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-80V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-14A	---	92	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	17.5	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	14	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-50V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-14A	---	20.5	---	ns
T <sub>r</sub>	Rise Time		---	32.2	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	123	---	
T <sub>f</sub>	Fall Time		---	63.7	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-25V, V <sub>GS</sub> =0V, f=1MHz	---	6516	---	pF
C <sub>oss</sub>	Output Capacitance		---	223	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	125	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-30	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =-14A, di/dt=-100A/μs, T <sub>J</sub> =25°C	---	31.2	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	31.97	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-25V,V<sub>GS</sub>=-10V,L=0.88mH,I<sub>AS</sub>=-28A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.



P-Ch 100V Fast Switching MOSFETs

Typical Characteristics

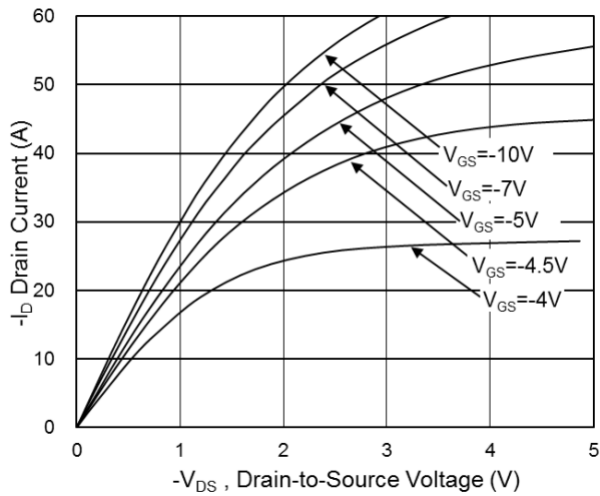


Fig.1 Typical Output Characteristics

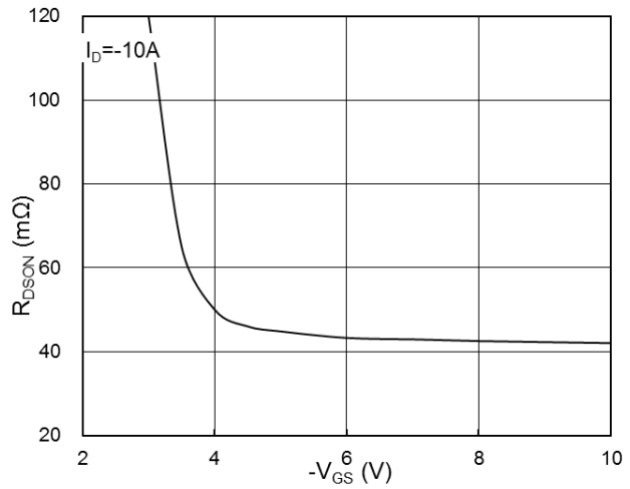


Fig.2 On-Resistance vs. G-S Voltage

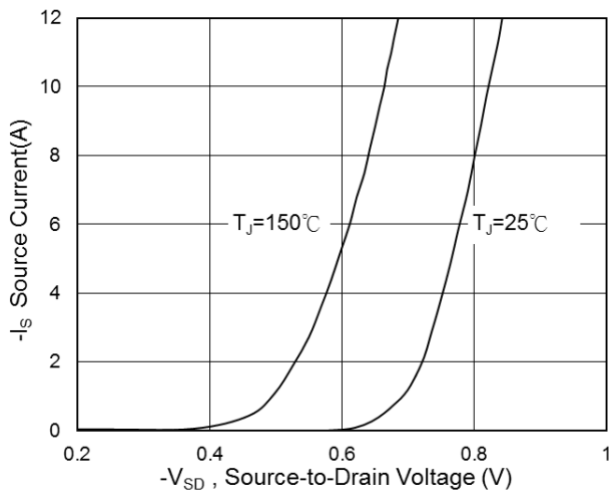


Fig.3 Typical S-D Diode Forward Voltage

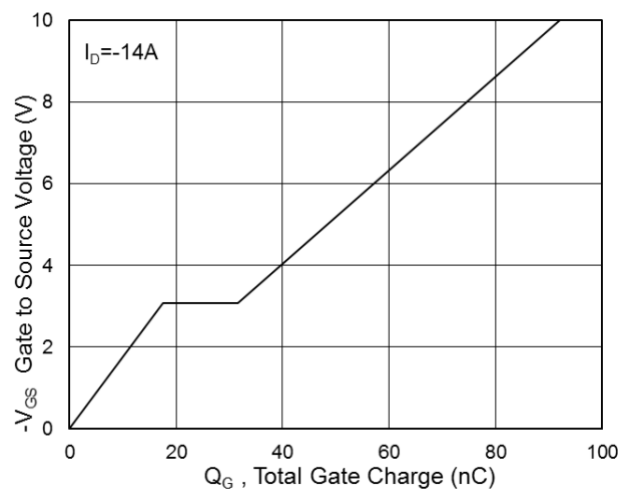


Fig.4 Gate-Charge Characteristics

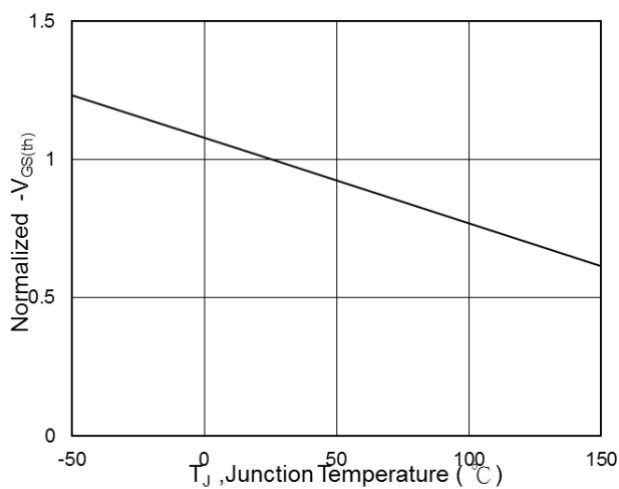


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

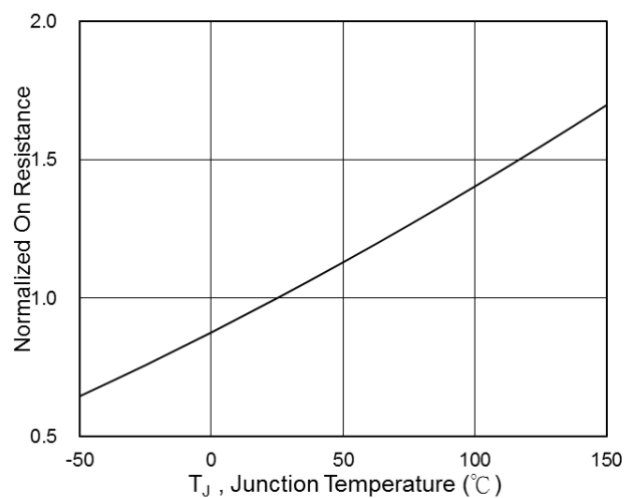
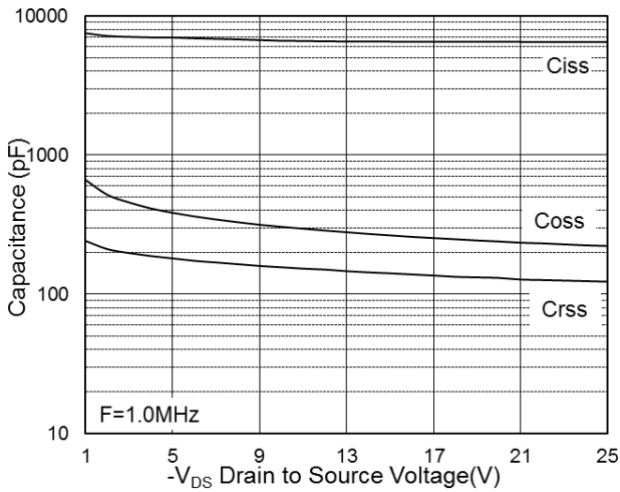


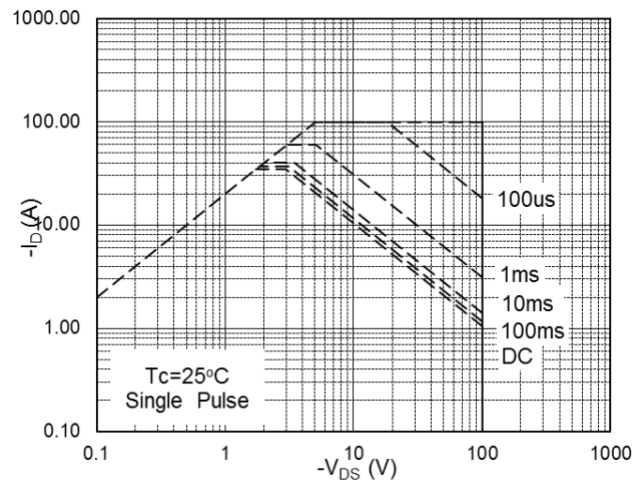
Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



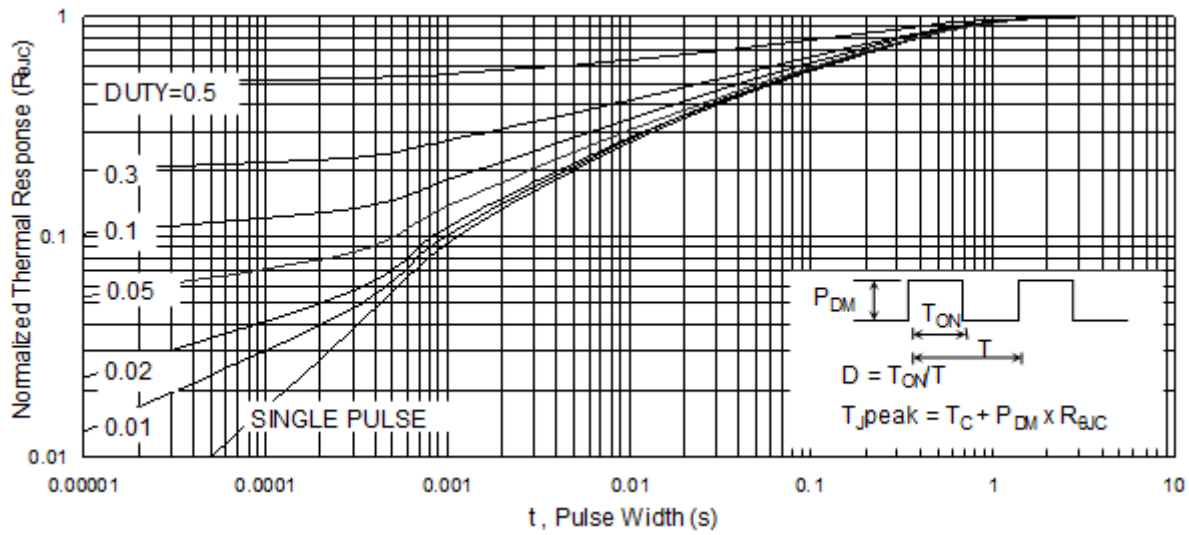
**P-Ch 100V Fast Switching MOSFETs**



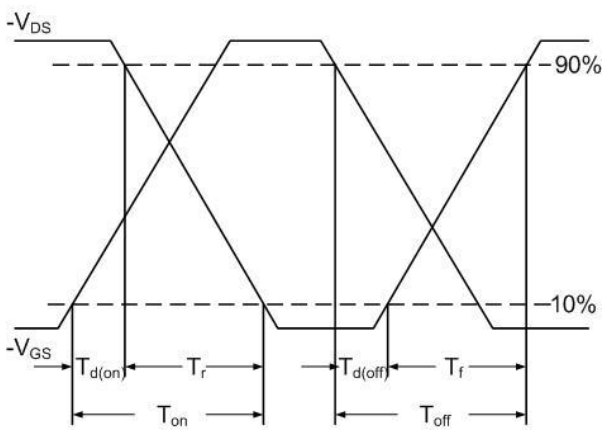
**Fig.7 Capacitance**



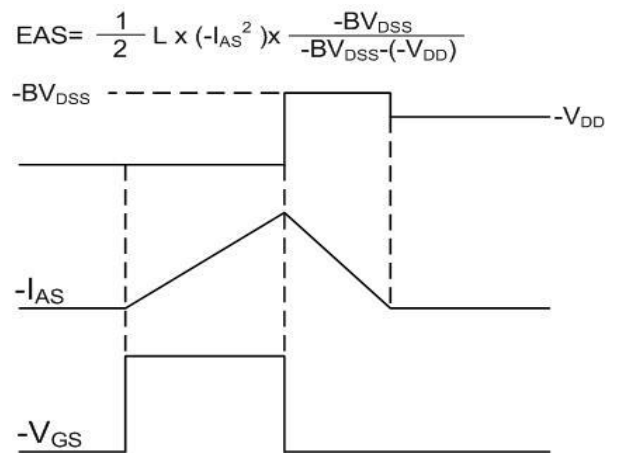
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



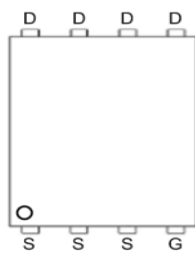
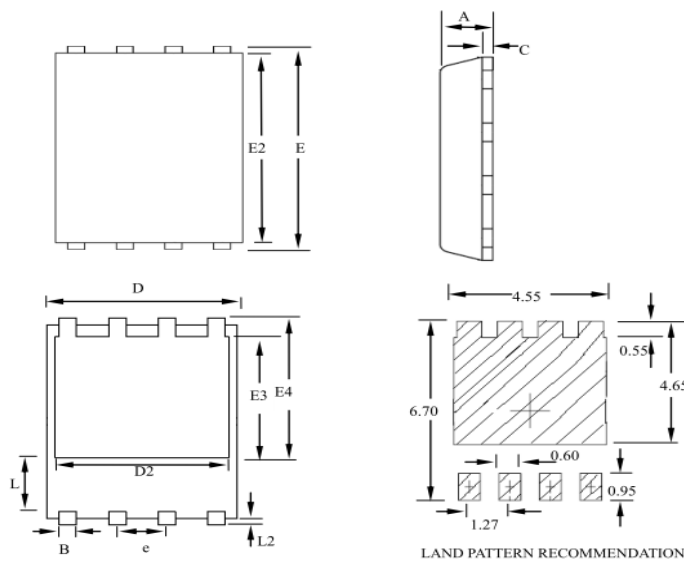
**Fig.11 Unclamped Inductive Waveform**



## Ordering Information

Part Number	Package code	Packaging
HSBA0139	PRPAK5*6	3000/Tape&Reel

PRPAK5\*6 Outline



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	--	1.20	0.031	--	0.047
B	0.30	--	0.51	0.012	--	0.020
C	0.15	--	0.35	0.006	--	0.014
D	4.80	--	5.30	0.189	--	0.209
D2	3.61	--	4.35	0.142	--	0.171
E	5.90	--	6.35	0.232	--	0.250
E2	5.42	--	5.90	0.213	--	0.232
E3	3.23	--	3.90	0.127	--	0.154
E4	3.69	--	4.55	0.145	--	0.179
L	0.61	--	1.80	0.024	--	0.071
L2	0.05	--	0.36	0.002	--	0.014
e	--	1.27	--	--	0.050	--